SN74SSTL16847 20-BIT SSTL_3 INTERFACE BUFFER WITH 3-STATE OUTPUTS

DGG PACKAGE

SCBS709A - OCTOBER 1997 - REVISED MAY 1998

•	Member of the Texas Instruments
	Widebus™ Family

- Supports SSTL_3 Signal Inputs and Outputs
- Flow-Through Architecture Optimizes PCB Layout
- Meets SSTL_3 Class I and Class II Specifications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Packaged in Plastic Thin Shrink Small-Outline Package

description

This 20-bit buffer is designed for 3-V to 3.6-V $\rm V_{CC}$ operation and SSTL_3 input levels.

Data flow from A to Y is controlled by the output-enable (\overline{OE}). When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74SSTL16847 is characterized for operation from 0° C to 70° C.

2	(TOP VI	EW)	
Y1 [Y2 [GND [Y3] Y4 [V _{DDQ} [Y5 [GND [Y7] Y10 [GND [OE [V _{REF} [GND [Y11] Y12 [V _{DDQ} [1 2 3	 64 63 62 61 59 58 57 56 54 53 52 51 50 49 48 47 46 45 44 	A1 A2 GND A3 A4 V _{CC} A5 A6 GND A7 A8 V _{CC} A9 A10 GND MC MC MC A11 A12 V _{CC}
Y13 [22] A13
Y14 [23] A14
GND [24	- 1] GND
Y15 [25	40	
Y16 [26	- 1] A16
	27	- 1	
Y17 [28] A17
Y18 [29] A18
GND [30] GND] A19
Y19 [Y20 [31	34 33	
120	32	33	

NC - No internal connection



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ſS	OUTPUT	
INPUTS		
Α	Y	
Н	Н	
L	L	
Х	Z	
	H L	

logic diagram (positive logic)



To 19 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} or V_{DDQ}	6 V
Input voltage range, V _I (see Note 1)	5 V
Output voltage range, V _O (see Notes 1 and 2) –0.5 V to V _{DDQ} + 0.	5 V
Input clamp current, I _{IK} (V _I < 0)	mΑ
Output clamp current, I_{OK} ($V_O < 0$)	mΑ
Continuous output current, $I_O (V_O = 0 \text{ to } V_{DDQ}) \dots \pm 50$	mΑ
Continuous current through each V _{CC} , V _{DDQ} or GND±100	mΑ
Package thermal impedance, θ_{JA} (see Note 3):	
Storage temperature range, T _{stg}	J°C
Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only,	
functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.	s not

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current will flow only when the output is in the high state and $V_O > V_{DDQ}$.

3. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 4)

				MIN	NOM	MAX	UNIT
VCC	Supply voltage		VDDQ		3.6	V	
VDDQ	Output supply voltage			3		3.6	V
VREF	Reference voltage (V _{REF} = $0.45 \times V_{DDQ}$)			1.3	1.5	1.7	V
VTT	Termination voltage		V _{REF} -50mV	VREF	V _{REF} +50mV	V	
VI	Input voltage			0		V _{CC}	V
VIH	AC high-level input voltage	All inputs		VREF+400mV			V
VIL	AC low-level input voltage	All inputs				V _{REF} -400mV	V
VIH	DC high-level input voltage	All inputs		V _{REF} +200mV			V
VIL	DC low-level input voltage	All inputs				V _{REF} -200mV	V
ЮН	High-level output current					-20	mA
IOL	Low-level output current	20 vel output current		20	ША		
TA	Operating free-air temperature			0		70	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	V _{CC}	MIN	TYP†	MAX	UNIT			
VIK		I _I = -18 mA		3 V			-1.2	V			
		I _{OH} = -100 μA	I _{OH} = -100 μA		V _{CC} -0.2	2					
∨он		I _{OH} = -16 mA		3 V	2.2			V			
		I _{OH} = -20 mA		3 V	2.1						
		l _{OL} = 100 μA		3 V to 3.6 V			0.2				
VOL		I _{OL} = 16 mA		2.1			0.5	V			
		I _{OL} = 20 mA		3 V	0.55		3 V		0.55).55	
	Data inputs, OE	V _I = 2.1 V or 0.9 V,	V _{REF} = 1.3 V or 1.7 V	3.6 V			±5	μΑ			
tı -	VREF	V _{REF} = 1.3 V or 1.7 V			3.0 V			±150	μΑ		
Ioz		V_{O} = 0.9 V or 2.1 V		3.6 V			±10	μΑ			
ICC		V _I = 2.1 V or 0.9 V,	IO = 0	3.6 V			90	mA			
0	Control inputs	VI = 2.1 V or 0.9 V		3.3 V		2		pF			
Ci	A port	v] = 2.1 v 01 0.9 v		3.3 V		2.5		hL			
Co	Y port	$V_{O} = 2.1 \text{ V or } 0.9 \text{ V}$		3.3 V		3.5		pF			

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25° C.



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switching characteristics over recommended operating free-air temperature range, Class I, $V_{REF} = V_{TT} = V_{DDQ} \times 0.45$ and $C_L = 10 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
^t pd	A	Y	1.5	3	ns
ten	OE	Y	1.5	4	ns
^t dis	ŌĒ	Y	1.6	4.9	ns

switching characteristics over recommended operating free-air temperature range, Class II, $V_{REF} = V_{TT} = V_{DDQ} \times 0.45$ and $C_L = 30 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	МАХ	UNIT
^t pd	A	Y	1.5	3	ns
ten	OE	Y	1.5	4.1	ns
^t dis	OE	Y	1.5	4.8	ns





 † V_{REF} = 0.45 V_{DDQ}

[‡]V_{IH} = V_{REF}+400mV (AC voltage levels)

§ VIL = VREF-400mV (AC voltage levels)

- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by apparently baying the following shared calculates: PRP < 10 MHz. Zo = 50.0 t < 1.25 mc/d.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 1.25 ns/V, t_f \leq 1.25 ns/V.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. $V_{TT} = V_{REF} = V_{DDQ} \times 0.45$
 - F. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - G. tpZL and tpZH are the same as ten.
 - H. tPLH and tPHL are the same as tpd.





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